

Amendments to the Specification:

Please replace the paragraph at page 13, lines 4-30 with the following amended paragraph:

Each of the disk boxes 10 accommodates disk modules 20 therein, supplies electric power to the disk modules 20, and controls electrical information of the disk modules 20. Two of the disk boxes 10 maintain a gap therebetween while opposing back surfaces (exhaust surfaces 103) thereof to each other and are symmetrically arranged as shown in FIG. 1B to form a unit 30. Four such units 30 are arranged up and down in four stages. The above-described gaps, with respect to these units 30 in four stages, collectively form a draft passage 30a. Undermentioned metal plates 22 and thermal conductive sheets 23 for cooling the disk modules 20 protrude into the draft passage 30a (heat radiation members), and protruding areas thereof become larger as they are located in a lower portion of a rack 50 as shown in FIG. 1B. Above the unit 30 located on the uppermost stage, eight electric exhaust fans 35 in total are provided so as to bridge over upper surfaces of the two disk boxes 10. Below the units 30 in four stages, two power supply sections 40 are arranged, which distribute AC power to undermentioned power supplies in the disk boxes 10 and to the exhaust fans 35. Specifically, in the rack 50, the units 30 in four stages, the exhaust fans 35 and the two power supply sections 40 are accommodated. The rack 50 is a standard one of which a front surface 103, facing inlet surfaces 101 of the disk boxes 10, is 19 inches in width. On each of the two front surfaces 103 of the rack 50, a louvered door provided with a filter therein is provided, and on an upper surface orthogonal to the front surfaces, a ceiling surface 50c enabling ventilation is provided.

Please replace the paragraph at page 18, line 18 to page 19, line 6 with the following amended paragraph:

In FIGS. 1B and 4, directions of airflows while the exhaust fans 35 are being operated are schematically shown by arrows. When the exhaust fans 35 are activated, the air outside the rack 50 passes through the louvers and filters of the front doors of the rack 50 and flows into the gaps defined between the disk modules 20. This air flows from the front surface (inlet ventilating surface 101) of the disk box 10 to the back surface (exhaust ventilating surface 102) thereof while colliding with the surfaces of the thermal conductive sheets 23 on

the side surfaces of the disk modules 20. In this process, heat on the side faces of the thermal conductive sheets 23 is dissipated into the air. Meanwhile, during the operation of the disk array apparatus 1, for example, frictional heat due to the rotation of the disks, resistance heat of the electronic circuit sections and the like are generated inside the magnetic disk device bodies 21. The heat propagates to the thermal conductive sheets 23 from the insides of the magnetic disk device bodies 21 through the cabinets 21c and the metal plates 22. Hence, the heat inside the bodies 21 is discharged into the air through the thermal conductive sheets 23.